

FEATURES

- High sensitivity
- Low capacitance
- Short switching time
- Surface mount package

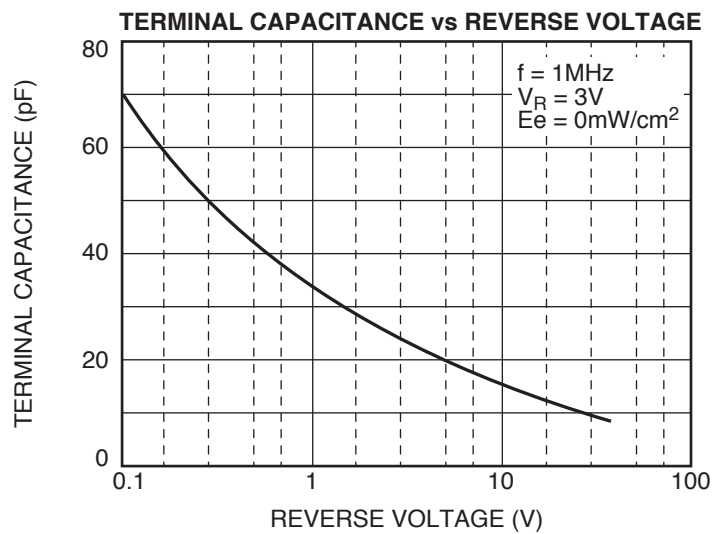
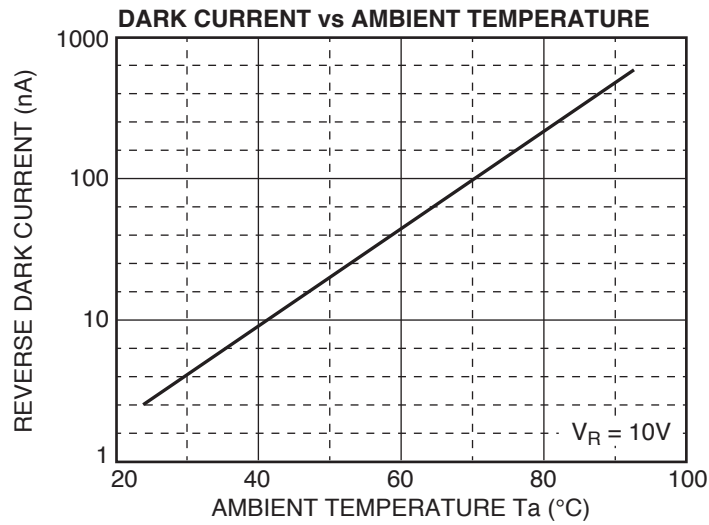
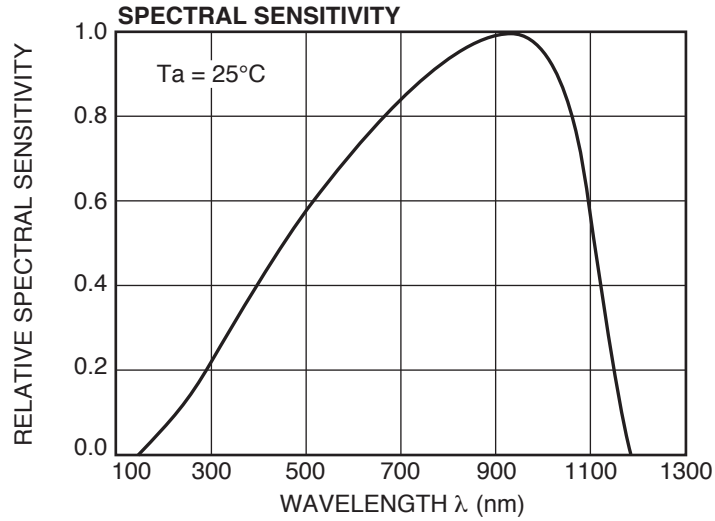


ELECTRO-OPTICAL CHARACTERISTICS AT 25°C

| PARAMETERS | TEST CONDITIONS | MIN | TYP | MAX | UNITS |
|--|---|-----|-------|------|-------|
| Range of Spectral Bandwidth, $\lambda_{0.5}$ | - | 400 | - | 1100 | nm |
| Wavelength of Peak Sensitivity, λ_P | - | - | 940 | - | nm |
| Responsivity | $\lambda_P = 940\text{nm}$ | - | 0.44 | - | A/W |
| Reverse Dark Current, I_P | $V_R = 10\text{V}$ | - | 5 | - | nA |
| Reverse Breakdown Voltage, B_{VR} | $I_R = 100\mu\text{A}$ | 32 | 170 | - | Volts |
| Total Capacitance, C_t | $V_R = 3\text{V}, f = 1\text{MHz}$ | - | 25 | - | pF |
| Rise/Fall Time, t_r/t_f | $V_R = 10\text{V}, R_L = 1\text{K}\Omega$ | - | 50/50 | - | nSec |

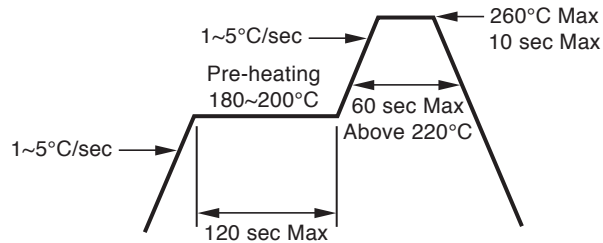
THERMAL PARAMETERS

| | |
|--|----------------|
| Operating Temperature Range | -25°C TO +85°C |
| Storage Temperature Range | -40°C TO +85°C |
| Power Dissipation at (or below) 25°C Free Air Temperature | 150mW |
| Soldering Temperature ¹ (Soldering time 5 sec max.) | 260°C |



¹ Soldering Conditions

1.0 Pb-free solder temperature profile



1.1 Reflow soldering should not be done more than twice

1.2 Do not stress the PD while soldering

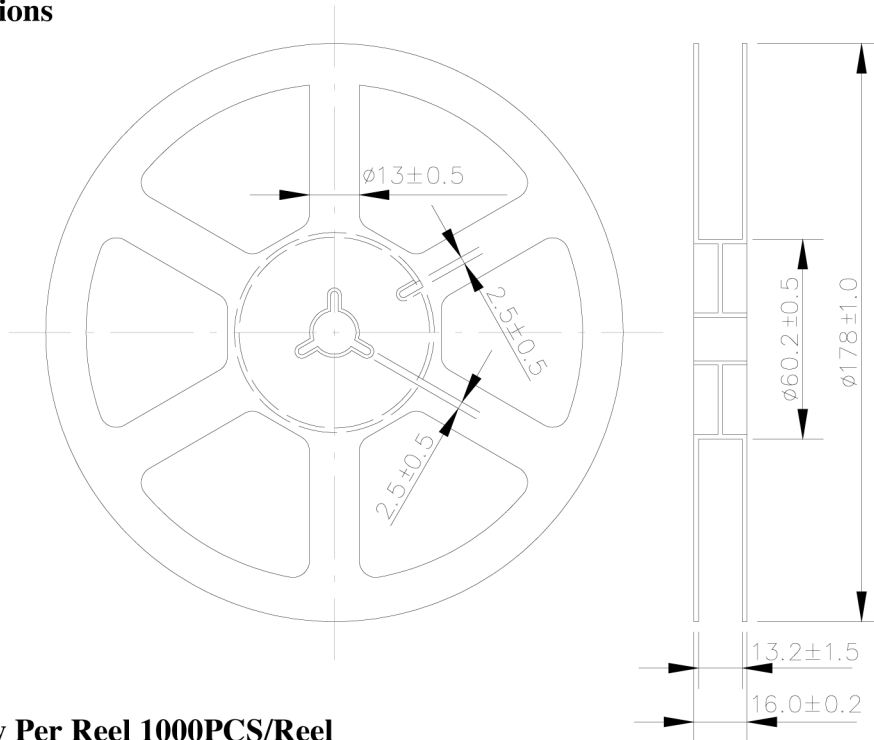
1.3 Don't flex the circuit board after soldering

2.0 Soldering Iron

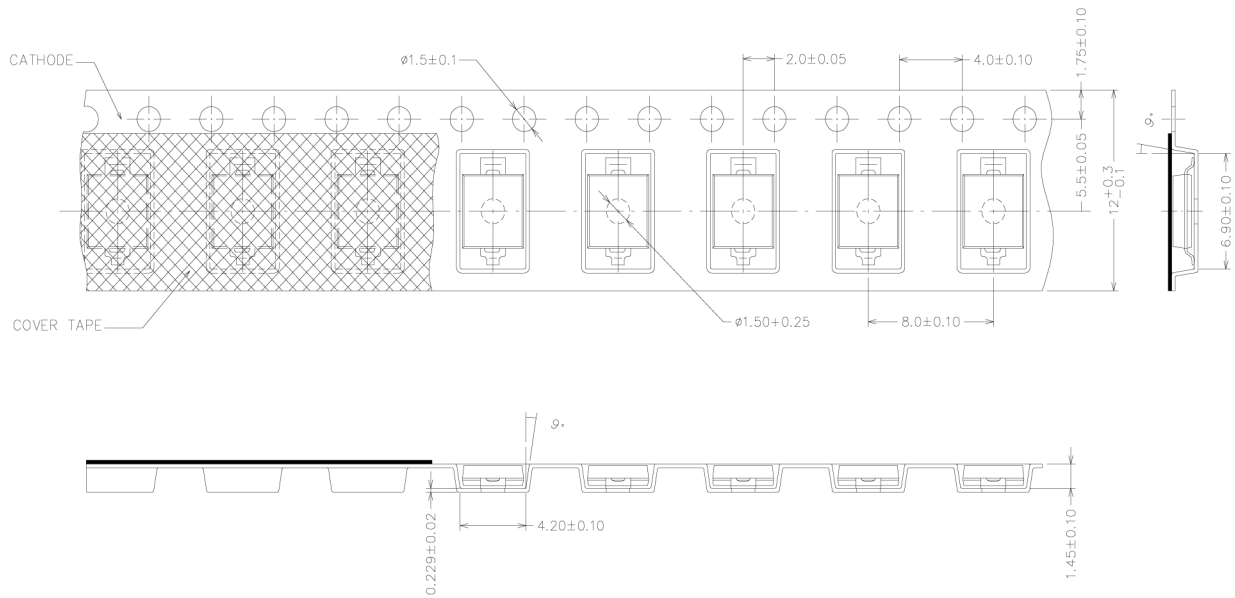
2.1 Each terminal should touch the tip of soldering iron (at 280°C) for less than for three seconds. Use a minimum two second interval between soldering each terminal. Use caution as product damage is often started during hand soldering.

2.2 The tip of soldering iron (at 280°) should be in contact with each terminal for less than three seconds. Pause for a minimum two second interval between soldering each terminal. Use caution as damage to the PD is often started during hand soldering.

Package Dimensions



Loaded Quantity Per Reel 1000PCS/Reel



Unit :mm